

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	1	("6580054").PN.	USPAT; USOCR	OR	OFF	2006/10/30 08:29
L10	1	9 and (stretch\$4 expand\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 08:38
L11	24	(die adj bond\$4) with (stretch\$4 expand\$4) with (tape stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 08:52
L12	3	(die adj bond\$4) with (stretch\$4 expand\$4) with (tape stage) same (pin push\$4 needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 08:52
S1	35	((die near5 bond\$3) with (wafer near5 (cut cutting divid\$3 divisi\$3))) same ((vacuum needle) near5 (transfer\$5 pickup pick picking))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 12:59
S2	123	((wafer near5 (cut cutting divid\$3 divisi\$3))) same (tape near5 (expand\$3 stretch\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 14:49
S3	6	((wafer near5 (cut cutting divid\$3 divisi\$3))) same (tape near5 (expand\$3 stretch\$3)) same ((clamp\$3 hold holding grip gripped gripping) near5 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 14:50
S4	2318	219/121.67, "121.72", "121.78", "121.81", "121"".""82".ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 15:28
S5	187	S4 and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 15:31
S6	40	S4 and ((die dice) with wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 08:29

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S7	679	((stretch\$4 expan\$7) near5 (tape ribbon support\$4)) same ((separat\$4 cut\$4 dicing) with (wafer dice die semiconduct\$4 silicon))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:00
S8	29	S7 same (pick\$4 with plac\$5 with (individual\$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:31
S9	16	S8 and (laser with (cut\$4 seperat\$4 dic\$4 machin\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:31
S10	0	S8 and laser not S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:30
S11	124	S7 same ((pick\$4 plac\$5 transfer\$4) near9 (individual\$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:01
S12	33	S11 and (laser with (cut\$4 seperat\$4 dic\$4 machin\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:31
S13	17	S12 not S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:47
S14	47	S7 and (push\$3 adj (up upward\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:45
S15	39	S7 and (push\$3 adj (up upward\$4)) with (stretch\$4 expan\$7 tape ribbon support\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:51
S16	43	S7 and (push\$3 adj (up upward\$4)) with (stretch\$4 expan\$7 tape ribbon support\$4 needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:53

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S17	43	S7 and ((push\$3 adj (up upward\$4)) pushup) with (stretch\$4 expan\$7 tape ribbon support\$4 needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:52
S18	27	S7 and (push\$3 adj (up upward\$4)) with (stretch\$4 expan\$7 tape ribbon support\$4 needle) and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:11
S19	17580	b23k026\$.ipc.	JPO	OR	ON	2006/03/01 10:59
S20	362997	h01I021\$.ipc.	JPO	OR	ON	2006/03/01 11:00
S21	379608	S19 S20	JPO	OR	ON	2006/03/01 11:00
S22	66	S21 and (((stretch\$4 expan\$7) near5 (tape ribbon support\$4)) same ((separat\$4 cut\$4 dicing) with (wafer dice die semiconduct\$4 silicon)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:00
S23	165	S21 and (((stretch\$4 expan\$7) and (tape ribbon support\$4)) and ((separat\$4 cut\$4 dicing) and (wafer dice die semiconduct\$4 silicon)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:01
S24	31	S23 and ((pick\$4 plac\$5 transfer\$4) and (individual\$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:05
S25	3	S24 and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:02
S26	1	S24 and ((push\$3 adj (up upward\$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:12
S27	1	S23 and ((push\$3 adj (up upward\$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:12
S28	1070	S21 and ((push\$3 adj (up upward\$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:13

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S29	93	S21 and ((push\$3 adj (up upward\$4)) pushup) and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:13
S30	60	S29 and (individual\$4 dice die semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:14
S31	2	S30 and (stretch\$4 expand\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:14
S32	4	(frame with ((push\$5 adj up\$5) pushup) with (expand\$4 stretch\$4)) and ((die dice dicing semiconductor) with (scrib\$4 cut\$4 seperat\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:52
S33	2	"20050221589"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:31
S34	27	laser with wafer with (divid\$4 cut\$4 etch\$4 street) with (stage tape support\$4) near3 (expand\$4 enlarg\$4 stretch\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:07
S35	6	(stage support\$4) near3 (expand\$4 enlarg\$4 stretch\$4) with (material fabric tape) with chamfer\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:08
S36	6	(stage support\$4 hold\$3) near3 (expand\$4 enlarg\$4 stretch\$4) with (material fabric tape) with chamfer\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:21
S37	1	(punch die) near3 (expand\$4 enlarg\$4 stretch\$4) with (material fabric tape sheet metal) with chamfer\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:22

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S38	217	((punch die stage support\$3 holder holding) with (expand\$4 enlarg\$4 stretch\$4) with (material fabric tape sheet metal)) and ((punch die stage support\$3 holder holding) with chamfer\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:23
S39	50	((punch die stage support\$3 holder holding) with (expand\$4 enlarg\$4 stretch\$4) with (material fabric tape sheet metal)) same ((punch die stage support\$3 holder holding) with chamfer\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:24
S40	19	((punch die stage support\$3 holder holding) with (expand\$4 enlarg\$4 stretch\$4) near5 (material fabric tape sheet metal)) same ((punch die stage support\$3 holder holding) with chamfer\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:31
S41	43	((punch die stage support\$3 holder holding) with (expand\$4 enlarg\$4 stretch\$4) near5 (material fabric tape sheet metal)) same ((punch die stage support\$3 holder holding) with (bevel\$4 chamfer\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:31
S42	24	S41 not S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:35
S43	1	("5997098").PN.	USPAT; USOCR	OR	OFF	2006/10/28 13:35
S44	1	S43 and bevel\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:35